



DEVICE TYPE:				SEMPAC, INC. Open-Pak™ Technologies www.sempac.com 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006				
CUSTOMER:		DIE SIZE:						
WIRE TYPE/ SIZE:		NO. OF WIRES:						
THIRD ANGLE PROJECTION UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER DO NOT SCALE DRAWING	REVISIONS					20 Lead 5.00mm x 5.00mm MLP Open-Pak Bonding Diagram		
	ECN NO.	DATE	DESCRIPTION	APPROVED				
	10481	10/21/05	PRODUCTION RELEASE	D.BENANDO		SIZE	PART NO.	REV
DRAWN BY	W. GRIFFITTS	DATE	10/21/05	PACKAGE SIZE:	5.00mm x 5.00mm	A	MLP5X5-20-OP-01	2
APP BY	P. FLASKERUD	DATE	10/21/05	DIE PAD SIZE:	3.10mm x 3.10mm	SCALE 32X	CAD FILE	SHEET 1 OF 1
							MLP5X5-20-OP-01-B-R2.DWG	